

**DDR4 DIMM**

TE Internal #: 2309413-4

SO DIMM Sockets, Small Outline (SO), Stack Height .362 in [9.2 mm], Right Angle Module Orientation, Surface Mount Mount, Cable-to-Board, DDR4 DIMM

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR4 SO DIMM SOCKETS

DRAM Type: **Small Outline (SO)**Stack Height: **9.2 mm [.362 in]**Module Orientation: **Right Angle**PCB Mounting Style: **Surface Mount**Connector System: **Cable-to-Board**
[All DDR4 SO DIMM SOCKETS \(39\)](#)
Features**Product Type Features**

Center Post	Without
DRAM Type	Small Outline (SO)
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Socket

Configuration Features

Center Key	Offset Left
Number of Keys	1
Module Orientation	Right Angle
Number of Positions	260
Number of Rows	2
Keying	Standard

Electrical Characteristics

DRAM Voltage	1.2 V
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Signal Characteristics



SGRAM Voltage	1.2 V
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Body Features

Retention Post Material	Stainless Steel
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Ejector Location	Both Ends
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Latch Material	High Temperature Thermoplastic
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Retention Post Location	Both Ends
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Module Key Type	Offset Left
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Ejector Type	Locking
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Connector Profile	High
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Contact Features

Socket Style	SO DIMM
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Contact Underplating Material	Nickel
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PCB Contact Termination Area Plating Material	Gold Flash
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Contact Base Material	Copper Alloy
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Contact Mating Area Plating Material	Gold
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Contact Mating Area Plating Material Thickness	.381 μ m[15 μ in]
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Contact Current Rating (Max)	.5 A
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Socket Type	Memory Card
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Termination Features

Insertion Style	Cam-In
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Mechanical Attachment

PCB Mount Retention	With
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PCB Mount Retention Type	Solder Peg
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PCB Mounting Style	Surface Mount
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Connector Mounting Type	Board Mount
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Housing Features

Centerline (Pitch)	.5 mm[.02 in]
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Housing Color	Black
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Housing Material	High Temperature Thermoplastic
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Dimensions

Stack Height	9.2 mm[.362 in]
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Row-to-Row Spacing	8.2 mm[.322 in]
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Usage Conditions

Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
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Operation/Application

Circuit Application	Power
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Method	Tape & Reel
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Packaging Quantity	500
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JAN 2022 (223) SVHC > Threshold: Not Yet Reviewed
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

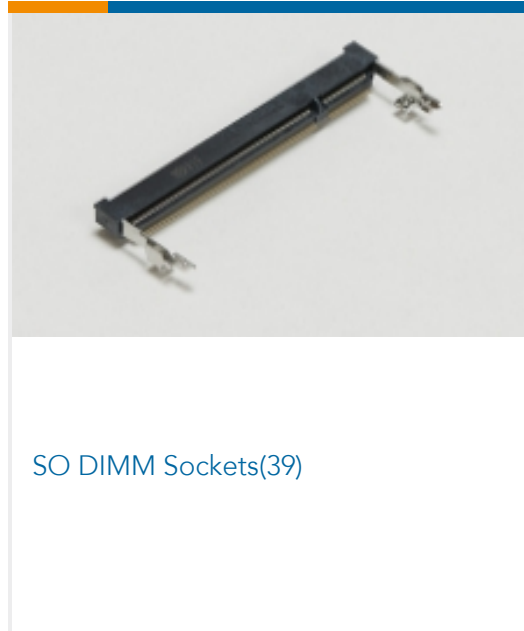
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

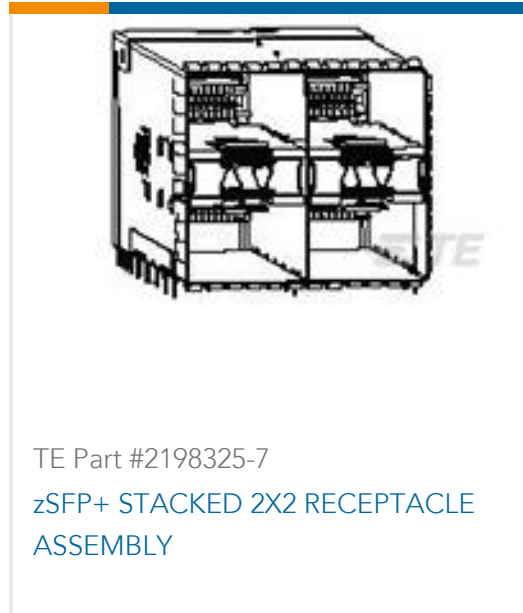
Compatible Parts



Also in the Series | DDR4 DIMM



Customers Also Bought





Documents

Product Drawings

[DDR4 SODIMM 260P 9.2H STD](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_2309413-4_1.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2309413-4_1.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2309413-4_1.3d_stp.zip](#)

English

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Product Specifications

[Application Specification](#)

English

Product Environmental Compliance

[Product Compliance](#)

English

[Product Compliance](#)

English